RoHS

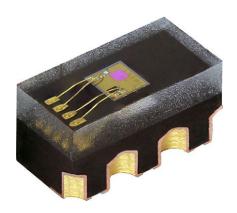
HALOGEN **FREE**

GREEN



Vishay Semiconductors

Low Power, High Sensitivity, I²C Ambient Light Sensor



DESCRIPTION

VEML3235SL is an advanced ambient light sensor with I²C protocol interface and is designed by the CMOS process. It is easy to operate via a simple I²C command.

VEML3235SL incorporates a photodiode, amplifiers, and analog circuits in a single chip. The best spectral sensitivity is used to closely capture real human eye responses. VEML3235SL has excellent temperature compensation and the robust refresh rate setting does not need an external RC low pass filter. Software shutdown mode is provided, which reduces power consumption to be less than 1 µA. VEML3235SL's operating voltage ranges from 2.6 V to 3.6 V. VEML3235SL can detect a wide range of ambient light power.

FEATURES

- Package type: surface-mount
- Dimensions (L x W x H in mm): 2.95 x 1.5 x 1.5
- · Integrated modules: ambient light sensor (ALS)
- Supply voltage range V_{DD}: 2.6 V to 3.6 V
- Communication via I²C interface
- I²C bus H-level range: 1.7 V to 3.6 V
- Floor life: 168 h, MSL 3, according to J-STD-020
- Low stand by current consumption: typ. 1 μA





- Handheld device
- Notebook
- · Consumer device
- · Industrial and medical application
- · Computing, and industrial devices and displays

AMBIENT LIGHT FUNCTION

- · High ALS sensitivity with minimum detectable intensity of 0.0021 lx/cnt supports low transmittance lens design
- Excellent temperature compensation
- · High dynamic detection resolution
- Software shutdown mode control

PRODUCT SUMMARY							
PART NUMBER	OPERATING VOLTAGE RANGE (V)	I ² C BUS VOLTAGE RANGE (V)	AMBIENT LIGHT RANGE (lx)	AMBIENT LIGHT RESOLUTION (lx)	OUTPUT CODE	ADC RESOLUTION PROXIMITY / AMBIENT LIGHT	
VEML3235SL	2.6 to 3.6	1.7 to 3.6	0.0021 to 17 867	0.0021	16 bit, I ² C	- / 16 bit	

ORDERING INFORMATION						
ORDERING CODE	PACKAGING	VOLUME (1)	REMARKS			
VEML3235SL	Tape and reel	MOQ: 2500	2.95 mm x 1.5 mm x 1.5 mm			

Note

(1) MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)							
PARAMETER TEST CONDITION SYMBOL MIN. MAX. UNIT							
Supply voltage		V_{DD}	0	4	V		
Operation temperature range		T _{amb}	-40	+85	°C		
Storage temperature range		T _{stg}	-40	+85	°C		

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)								
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT		
Supply voltage		V_{DD}	2.6	3.3	3.6	V		
Shut down current (1)(2)	V _{DD} is 3.3 V	I _{sd}	=	1	-	μΑ		
Supply current (1)	V _{DD} is 3.3 V	I _{DD}	-	250	-	μΑ		
I ² C clock rate range		f _{SCL}	10	-	400	kHz		
I ² C bus input H-level range	V _{DD} is 3.3 V	V _{ih}	1.2	-	V_{DD}	V		
I ² C bus input L-level range	V _{DD} is 3.3 V	V _{il}	0	-	0.4	V		
Digital resolution (LSB count) (2)	With DG = x 2, Gain = x 4		-	0.0021	-	lx/step		
Detectable minimum illuminance (2)	With DG = x 2, Gain = x 4	E _{V min.}	-	0.0021	-	lx		
Detectable maximum illuminance (3)	With DG = x 1, Gain = x 1	E _{V max.}	=	17 867	-	lx		

Notes

- $^{(1)}$ V_{DD} = 3.3 V, temperature: 25 °C
- $^{(2)}$ IT = 800 ms
- (3) IT = 50 ms

CIRCUIT BLOCK DIAGRAM

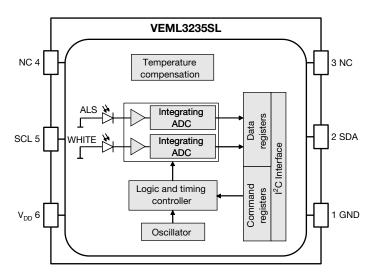


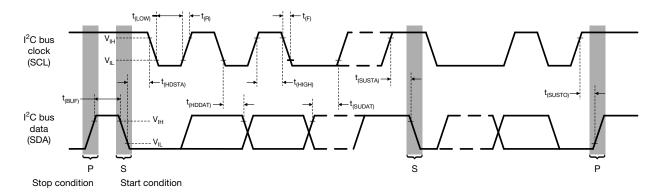
Fig. 1 - Block Diagram

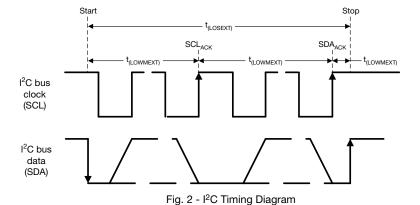


I ² C TIMING CHARACTERISTICS (T	_{amb} = 25 °C,	unless othe	rwise specif	ied)		
DADAMETED	SYMBOL	STANDARD I		FAST MODE (1)		LINIT
PARAMETER	STIMBUL	MIN.	MAX.	MIN.	MAX.	UNIT
Clock frequency	f _(SMBCLK)	10	100	10	400	kHz
Bus free time between start and stop condition	t _(BUF)	4.7	-	1.3	-	μs
Hold time after (repeated) start condition; after this period, the first clock is generated	t _(HDSTA)	4.0	-	0.6	-	μs
Repeated start condition setup time	t _(SUSTA)	4.7	-	0.6	-	μs
Stop condition setup time	t _(SUSTO)	4.0	-	0.6	-	μs
Data hold time	t _(HDDAT)	-	3450	-	900	ns
Data setup time	t _(SUDAT)	250	-	100	-	ns
I ² C clock (SCL) low period	t _(LOW)	4.7	-	1.3	-	μs
I ² C clock (SCL) high period	t _(HIGH)	4.0	-	0.6	-	μs
Clock / data fall time	t _(F)	-	300	-	300	ns
Clock / data rise time	t _(R)	-	1000	-	300	ns

Note

 $^{^{(1)}}$ Data based on standard I2C protocol requirement, not tested in production





PARAMETER TIMING INFORMATION

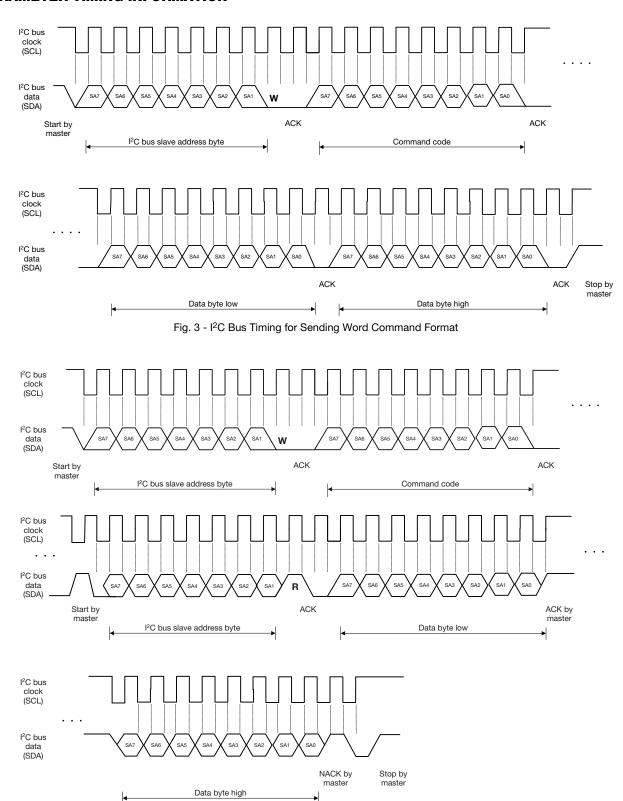


Fig. 4 - I²C Bus Timing for Receive Word Command Format

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

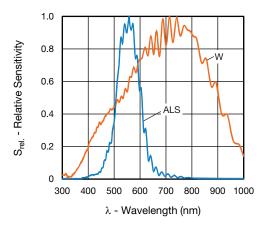


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

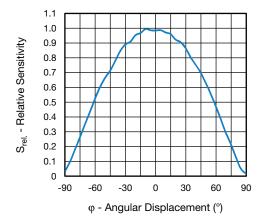


Fig. 6 - Relative Sensitivity vs. Angular Displacement

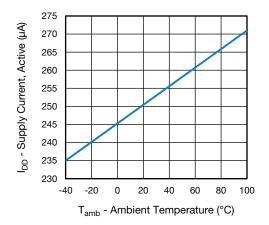


Fig. 7 - Supply Current vs. Ambient Temperature

APPLICATION INFORMATION

1. Pin Connection With the Host

VEML3235SL is a cost effective solution with I²C interface. The standard serial digital interface easily accesses "light intensity" without using complex calculations and programming by an external controller.

The additional capacitor near the V_{DD} pin in the circuit is used for power supply noise rejection. The value is recommended at 0.1 μ F. The pull-high resistors for the I^2 C bus design are recommended to be 2.2 $k\Omega$.

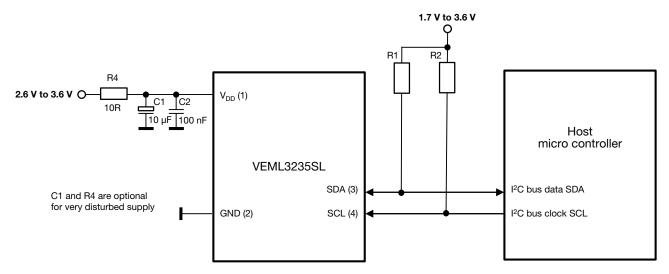


Fig. 8 - Hardware Pin Connection Diagram (Slave Address 0x10)

Digital Interface

VEML3235SL contains a command register written via the I²C bus. All operations can be controlled by the command register. The simple command structure allows the user to easily program the operation setting and latch the light data from VEML3235SL. VEML3235SL's I²C command format description for read and write operations between VEML3235SL and the host is shown in Fig. 9. The white areas indicate the host activity and the gray areas indicate VEML3235SL's acknowledgement of the host access activity.



Fig. 9 - Command Protocol Format



Command Register Format

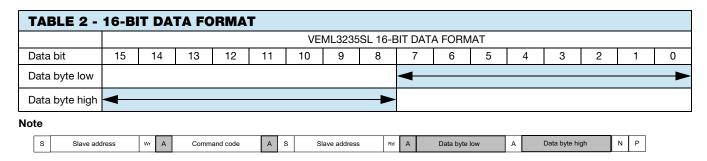
VEML3235SL uses 0x10 slave address for 7-bit I^2C addressing protocol. VEML3235SL has 16-bit resolution for each channel (ALS and W).

COMMAND CODE	REGISTER NAME	DATE BYTE LOW / HIGH	BIT	FUNCTION DESCRIPTION	R/W
	Reserved		7	Set 0	
	ALS/W_IT	L	6:4	ALS/W integration time setting $(0:0:0) = 50$ ms $(0:0:1) = 100$ ms $(0:1:0) = 200$ ms $(0:1:1) = 400$ ms $(1:0:0) = 800$ ms	
	Reserved		3:1	Set 0	
	SD		0	Shutdown BG and LDO with SD = 1 (default)	
0x00	SD0		7	Shutdown ALS and white channel with SD0 = 1 (default)	R/W
	Reserved		6	Set 0	n/w
	DG		5	0 = x 1, 1 = x 2	
	Gain	н	4:3	(0:0) = x 1 (0:1) = x 2 (1:0) = reserved (1:1) = x 4	
	Reserved		2:1	Set 0	
	Reserved		0	Set 1	
0x02	Reserved	L	7:0	Set 0	
0x02	Reserved	Н	7:0	Set 0	
0x04	W_LSB	L	7:0	W LSB data	
0.04	W_MSB	Н	7:0	W MSB data	
0x05	ALS_LSB	L	7:0	ALS LSB data	R
0.000	ALS_MSB	Н	7:0	ALS MSB data	П
0x09	ID_L	L	7:0	ID part number: 3235 = 0011 0101	
0,00	Reserved	Н	7:0	Reserved	



Data Access

VEML3235SL has 16-bit high resolution sensitivity for each channel. To represent the 16-bit data, it has to apply two bytes. One byte is for LSB and the other byte is for MSB. The host needs to follow the read word protocol. The data format shows as below.



• Data byte low represents LSB and data byte high represents MSB

The table below shows these dependencies:

RESOLUTIO	RESOLUTION AND MAXIMUM DETECTION RANGE AT DG = 1									
	GAIN: x 4	GAIN: x 2	GAIN: x 1		GAIN: x 4	GAIN: x 2	GAIN: x 1			
IT (ms)	TYPIC	AL RESOLUTION	(lx/cnt)		MAXIMUM	POSSIBLE ILLUM	INATION (Ix)			
800	0.00426	0.00852	0.01704		279	558	1117			
400	0.00852	0.01704	0.03408		558	1117	2233			
200	0.01704	0.03408	0.06816		1117	2233	4467			
100	0.03408	0.06816	0.13632		2233	4467	8934			
50	0.06816	0.13632	0.27264		4467	8934	17 867			

RESOLUTIO	RESOLUTION AND MAXIMUM DETECTION RANGE AT DG = 2									
	GAIN: x 4	GAIN: x 2	GAIN: x 1		GAIN: x 4	GAIN: x 2	GAIN: x 1			
IT (ms)	TYPIC	AL RESOLUTION	(lx/cnt)		MAXIMUM	POSSIBLE ILLUM	INATION (Ix)			
800	0.00213	0.00426	0.00852		140	279	558			
400	0.00426	0.00852	0.01704		279	558	1117			
200	0.00852	0.01704	0.03408		558	1117	2233			
100	0.01704	0.03408	0.06816		1117	2233	4467			
50	0.03408	0.06816	0.13632		2233	4467	8934			

Example:

If the 16-bit word of the ALS data shows: 0000 0101 1100 1000 = 1480 (dec.), the programmed Gain = x 1, the digital gain DG = x 1 and the integration time is 100 ms, the corresponding lux level is: light level [lx] = 1480 x 0.13632 = 202 lx.

For detailed description about set-up and more application related information see application note: "Designing VEML3235SL into an Application".



PACKAGE INFORMATION in millimeters

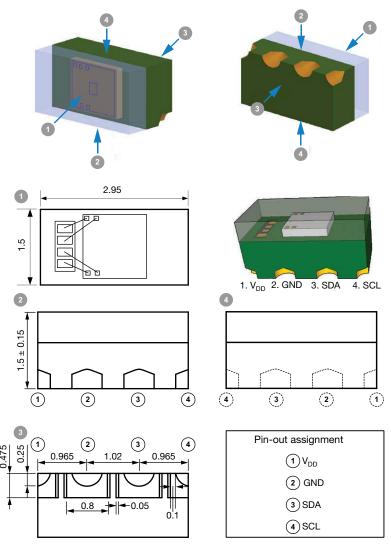


Fig. 10 - VEML3235SL Package Dimensions

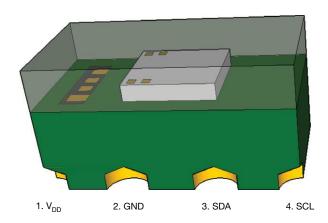


Fig. 11 - VEML3235SL Package Dimensions

LAYOUT NOTICE AND REFERENCE CIRCUIT in millimeters

Pad and Circuit Layout Reference

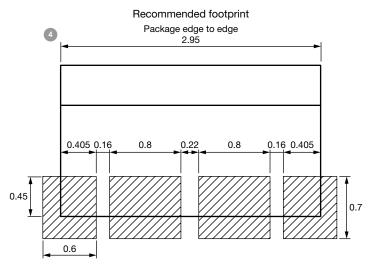


Fig. 12 - VEML3235SL PCB Layout Footprint

TAPE AND REEL DIMENSIONS in millimeters

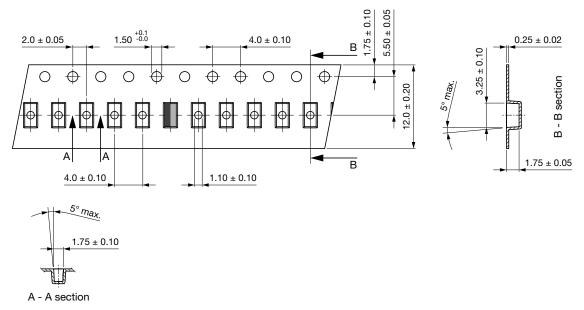


Fig. 13 - VEML3235SL Package Carrier Tape



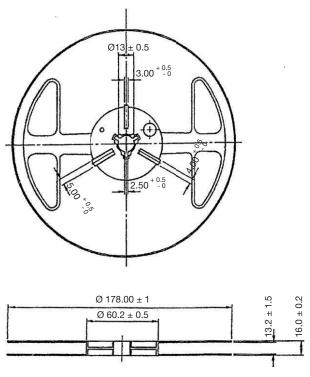


Fig. 14 - Reel Dimension

RECOMMENDED STORAGE AND REBAKING CONDITIONS								
PARAMETER	CONDITIONS	MIN.	MAX.	UNIT				
Storage temperature		5	50	°C				
Relative humidity		-	60	%				
Open time		-	168	h				
Total time	From the date code on the aluminized envelope (unopened)	-	12	months				
Debaking	Tape and reel: 60 °C	-	22	h				
Rebaking	Tube: 60 °C	-	22	h				

RECOMMENDED INFRARED REFLOW

Soldering conditions which are based on J-STD-020 C

IR REFLOW PROFILE CONDITION							
PARAMETER	CONDITIONS	TEMPERATURE	TIME				
Peak temperature		255 °C + 0 °C / - 5 °C (max.: 260 °C)	10 s				
Preheat temperature range and timing		150 °C to 200 °C	60 s to 180 s				
Timing within 5 °C to peak temperature		-	10 s to 30 s				
Timing maintained above temperature / time		217 °C	60 s to 150 s				
Timing from 25 °C to peak temperature		-	8 min (max.)				
Ramp-up rate		3 °C/s (max.)	-				
Ramp-down rate		6 °C/s (max.)	-				

Recommend Normal Solder Reflow is 235 °C to 255 °C

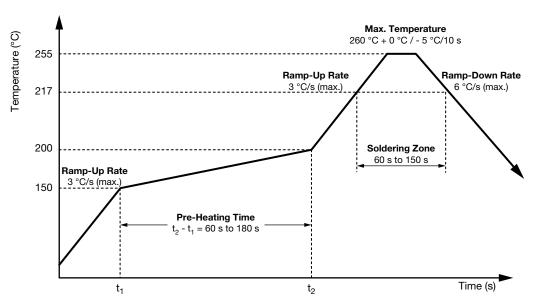


Fig. 15 - VEML3235SL Solder Reflow Profile Chart

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: $T_{amb} < 30~^{\circ}\text{C},~\text{RH} < 60~\%$

Moisture sensitivity level 3, according to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



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